

TO-3216BY-MWF

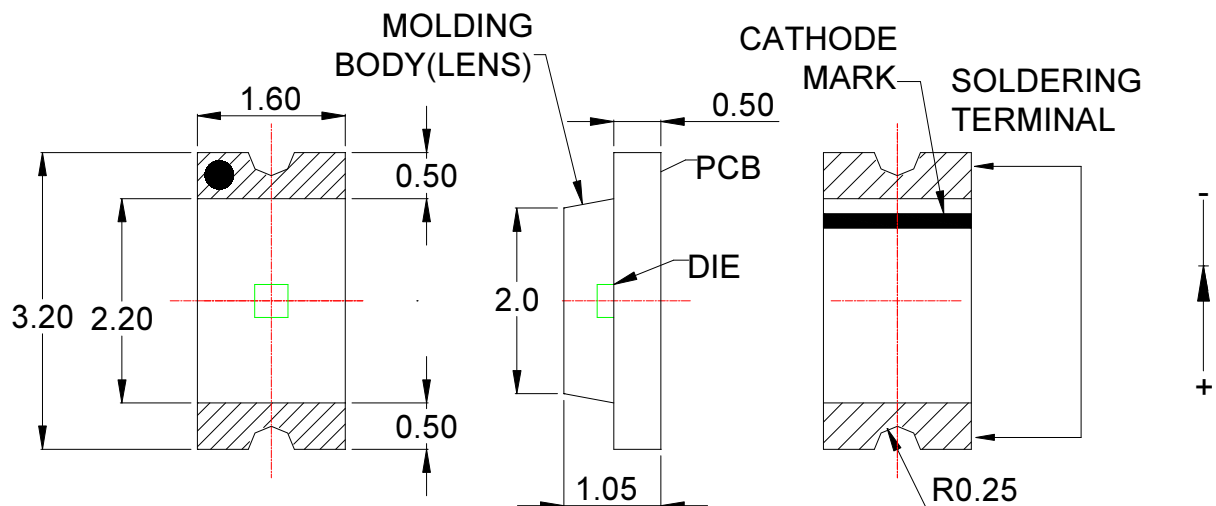
Surface Mount Device LED

Part Number	Chip		Lens Color
	Material	Source Color	
TO-3216BY-MWF	InGaN	Ultra White	Yellow Diffused

Features

- IC compatible
- Compatible with automatic placement equipment
- Compatible with infrared and vapor phase reflow solder process
- Top view type
- Package in 8 mm tape on 7" diameter reel
- RoHS compliant
- Moisture sensitivity level: level 3

Dimensions



Notes:

1. All dimensions are in millimeters.
2. Tolerance is ± 0.1 mm unless otherwise noted.

Absolute Maximum Rating @ Ta=25°C

Parameter	Maximum Rating	Unit
Peak Forward Current (1/10 Duty Cycle, 0.1ms Pulse Width)	80	mA
Power Dissipation	105	mW
Continuous Forward Current	25	mA
Reverse Voltage	5	V
Electro-Static Discharge(MM)	300	V
Electro-Static Discharge(HBM)	3000	V
Operating Temperature Range	-55°C to +85°C	
Storage Temperature Range	-55°C to +105°C	
IR Reflow Soldering Profile For Lead Free Soldering	260°C	

Electrical / Optical Characteristic @ Ta=25°C

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Condition
Luminous Intensity	I _v	321		917	mcd	I _F =20mA
Viewing Angle	2θ _{1/2}		120		deg	I _F =20mA
Forward Voltage	V _F		3.2		V	I _F =20mA
Reverse Current	I _R			10	μA	V _R =5V
Color Temperature	T _c		8000		K	I _F =20mA
Chromaticity Coordinates	X		0.295			I _F =20mA
Chromaticity Coordinates	Y		0.29			I _F =20mA